

Low Density Polyethylene PB208

Description:

PB208 is a low density polyethylene with no additives. This grade shows excellent processability being indicated for low viscosity required applications. Injection molded products with this resin shows good flow and flexibility properties.

Additive:

No additives present

Applications:

Masterbatches;

Covers and injected parts with large flat area.

Process:

Injection Molding

Control Properties:

	ASTM Method	Units	Values
Melt Flow Rate (190/2.16)	D 1238	g/10 min	22
Density	D 1505	g/cm3	0.923

Properties:

Plaque Properties^a

	ASTM Method	Units	Values
Tensile Strength at Yield	D 638	MPa	10
Tensile Strength at Break	D 638	MPa	8
Tensile Elongation at Break	D 638	%	139
Flexural Modulus – 1% Secant	D 790	MPa	250
Shore D Hardness	D 2240	-	45
Environmental Stress Cracking Resistanceb	D 1693	h/F50	-
Vicat Softening Temperature at 10 N	D 1525	°C	87

⁽a) Test specimens prepared from compression molded sheet made according to ASTM D 4703.

Recommended Processig Conditions: Injection Molding

- Temperature profile.......160 to 230°C
- Mold temperature......5 to 25°C

Final Remarks:

- This resin meets the requirements for olefin polymers as defined in 21 CFR, section 177.1520 issued by FDA Food and Drug Administration in force on the date of publication of this specification. The additives present are covered in appropriate regulation by FDA
- The information presented in this Data Sheet reflects typical values obtained in our laboratories, but should not be considered as absolute or as warranted values. Only the properties and values mentioned on the Certificate of Quality are considered as guarantee of the product. In some applications, Braskem has developed tailor-made resins to reach specific requirements.
- In case of doubt regarding utilization, or for other applications, please contact our Technical Assistance
- For information about safety, handling, individual protection, first aids and waste disposal, please see MSDS. CAS Registry number: 009002-88-4. The mentioned values in this report can be changed at any moment without Braskem previous communication.

 Braskem does not recommend this grade for packages, parts or any kind of product manufacture that will be used for storage or contact with solution that
- will have internal contact with human body.
- The content of this Data Sheet replaces previous revisions published for this product.

 This resin does not contain the substance Bisphenol A (BPA, CAS # No. 80-05-7) in its composition.





⁽b) Compression molded 2 mm thickness, 0.3 mm notched-plaques. 100% Igepal. 50°C